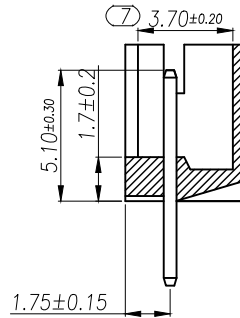
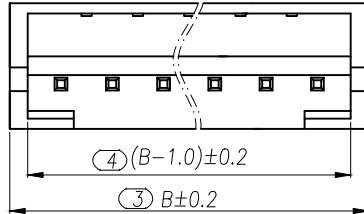
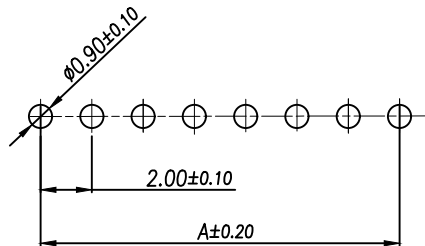
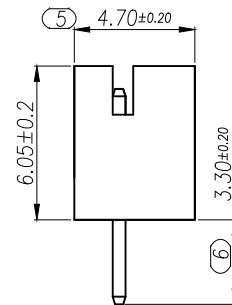
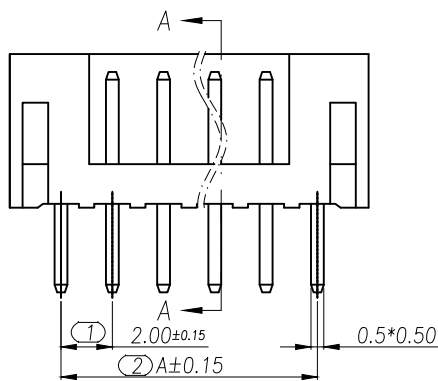


PRELIMINARY
DESIGN IS SUBJECT
TO CHANGE WITHOUT
PRIOR NOTICE



SECTION A-A



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

Part No	PIN	A	B
XY-PH2.0-2PZZ	2	2	6
XY-PH2.0-3PZZ	3	4	8
XY-PH2.0-4PZZ	4	6	10
XY-PH2.0-5PZZ	5	8	12
XY-PH2.0-6PZZ	6	10	14
XY-PH2.0-7PZZ	7	12	16
XY-PH2.0-8PZZ	8	14	18
XY-PH2.0-9PZZ	9	16	20
XY-PH2.0-10PZZ	10	18	22
XY-PH2.0-11PZZ	11	20	24
XY-PH2.0-12PZZ	12	22	26
XY-PH2.0-13PZZ	13	24	28
.....	...	...	...
XY-PH2.0-20PZZ	20	(20-1)*2	(20+1)*2

技术要求:

1. 塑件材料: PA66 (UL-94V-0)
2. 接触件: 黄铜镀锡
3. 接触电阻: $\leq 10m\Omega$
4. 绝缘电阻: $\geq 1000M\Omega$
5. 额定电压: 250V AC DC
6. 额定电流: 2.0A AC DC
7. 耐压: 能承受 1000V AC/Minute
8. 工作温度: $-25^{\circ}\sim +85^{\circ}$
9. 可焊性试验: 浸锡面积 $\geq 95\%$ 温度 $220^{\circ}\pm 5^{\circ}$, 时间 2.5 ± 0.5 秒
10. 铅和铜等六大有害物质含量要符合环保要求

2	Contact	Brass	n*1	电镀(锡): 整个表面镀底镍30u"MIN, 再镀锡80u"MIN.
1	Wafer	PA66(UL94V-0)	1	本色
序号	名称	材料	数量	备注

DIMENSION in mm		厦门市辛译精密电子有限公司 Xiamen XinYi Xyeconn Electronics Co.,Ltd				
TOLERANCE UNLESS OTHERWISE SPECIFIED						
.X±0.35	X.*± 5°	APR. <i>Alex</i>	TITLE: WAFER 2.0mm H6.0mm 180° DIP			
.XX±0.25	.X.*± 3°	CHK. <i>Jack</i>	DWG NO. XY-PH2.0-NPZZ			
.XXX±0.15	.XX.*± 1°	DRA. <i>Can</i>	PROJ. 		CUSTOMER DRAWING	
			SIZE A4	SCALE 1:1	SHEET 1 / 1	REV. A